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**INFORMATION DISCLOSURE
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Complete if Known

Application Number	09/483881
Filing Date	January 18, 2000
First Named Inventor	Ahn, Kie
Group Art Unit	2812
Examiner Name	Nguyen, Ha

Sheet 1 of 1

Attorney Docket No: 303.672US1

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Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date if Appropriate
lm	US-6,120,641	10/19/2000	Stevens, E. Henry , et al.	156	345.22	08/03/1998
	US-6,277,263	08/21/2001	Chen, Linlin	205	182	08/31/1999
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	US-6,368,966	04/09/2002	Krishnamoorthy, Ahila , et al.	438	687	08/31/1999
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Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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EXAMINER

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Substitute Disclosure Statement Form (PTO-1449)

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Sheet 1 of 7

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Complete if Known

Application Number	09/483881
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First Named Inventor	Ahn, Kie
Group Art Unit	2812
Examiner Name	Nguyen, Ha

Attorney Docket No: 303.672US1

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Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
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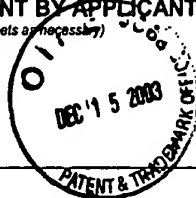
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Application Number 09/483881
 Filing Date January 18, 2000
 First Named Inventor Ahn, Kie
 Group Art Unit 2812
 Examiner Name Nguyen, Ha

Attorney Docket No: 303.672US1

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✓	US-5,510,645	04/23/1996	Fitch, J. T., et al.	257	522	01/17/1995
	US-5,529,956	06/25/1996	Morishita, Y.	437	195	09/28/1994

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PTO/SB/00A(10-01)
 Approved for use through 10/31/2002. OMB 051-0031

US Patent & Trademark Office U.S. DEPARTMENT OF COMMERCE

Complete if Known	
Application Number	09/483881
Filing Date	January 18, 2000
First Named Inventor	Ahn, Kie
Group Art Unit	2812
Examiner Name	Nguyen, Ha
Attorney Docket No: 303.672US1	

Sheet 3 of 7

in	US-5,534,731	07/09/1996	Cheung, Robin	257	759	10/28/1994
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	US-5,675,187	10/07/1997	Numata, K., et al.	257	758	05/16/1996
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✓	US-5,976,710	11/02/1999	Sachdev, K. G., et al.	428	620	04/10/1997

EXAMINER

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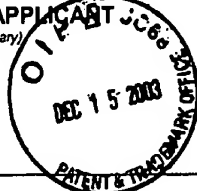
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PTO/SB/05A (10-01)
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Application Number	09/483881
Filing Date	January 18, 2000
First Named Inventor	Ahn, Kie
Group Art Unit	2812
Examiner Name	Nguyen, Ha
Attorney Docket No: 303.672US1	

Sheet 4 of 7

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✓	US-6,383,920	05/07/2002	Wang, P., et al.	438	639	01/10/2001
✓	US-6,563,219	05/13/2003	Ireland, Phillip, et al.	257	758	11/02/2001

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Attorney Docket No: 303.672US1

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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ⁴
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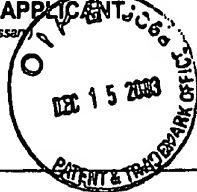
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		Application Number	09/483881
		Filing Date	January 18, 2000
		First Named Inventor	Ahn, Kie
		Group Art Unit	2812
		Examiner Name	Nguyen, Ha
Sheet 6 of 7		Attorney Docket No: 303.672US1	

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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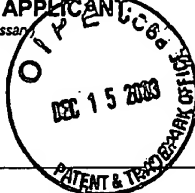
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Application Number	09/483881
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lm		SHIEH, B. , et al., "Air-Gap Formation During IMD Deposition to Lower Interconnect Capacitance", <u>IEEE Electron Device Letters</u> , 19(1), (1998),16-18	
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